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[illegible]

of forming a HSQFN (High Speed Quad Flat Pack) package, comprising:  
a leadframe with bonding pads;  
a die;  
bonding wires between said die and said bonding pads;  
a compound having electrical connection; and  
a die by compound from a substrate;  
the method comprising:  
removing said leadframe from the compound;  
exposing a lower surface of said leadframe to expose a lower surface of said die;  
separating said die from said leadframe;  
and  
forming individual packages;  
and said compound.

The method of claim 1, further comprising:  
removing said leadframe to form an individual package;  
said leadframe, therefrom;  
and die pads.

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of forming a HSQFN (High Speed Quad Flat Pack) package, comprising:  
a leadframe with bonding pads;  
a die;  
bonding the die on said die pad;  
forming a bond between said bonding pads and said die;  
removing said bond connection;  
removing said die by compound from said package;  
removing said leadframe from said package;  
removing said bond frame to expose a lower surface of said die;  
thereby separating said die from said package; and  
removing each individual package from said compound.

Method of claim 1, further comprising:  
removing said leadframe to form an individual package;  
removing said leadframe, thereby exposing said die and die pads.

of forming a HSQFN (High Speed Quad Flat Pack) package, comprising:  
a leadframe with bonding pads;  
a die;  
bonding the die on said die pad;  
forming a bond between said bonding pads and said die;  
removing said bond connection;  
removing said die by compound from said package;  
removing said leadframe from said package;  
removing said bond frame to expose a lower surface of said die;  
thereby separating said die from said package;  
and  
repeating each individual package formation step on said compound.

Method of claim 1, further comprising:  
removing said leadframe to form an individual package;  
removing said leadframe, thereby exposing said die and die pads.

of forming a HSQFN (High Speed Quad Flat Pack) package, comprising:  
a leadframe with bonding pads;  
a die;  
bonding the die on said die pad;  
forming bonds between said bonding pads and said die;  
sealing the electrical connection;  
removing the die by compound from a carrier;  
trimming said leadframe from the carrier;  
removing the leadframe to expose a lower surface;  
thereby separating said leadframe from the carrier;  
and  
mounting each individual package on a substrate and said compound.

The method of claim 1, further comprising:  
removing the leadframe to form an interconnect;  
on said leadframe, there are formed conductive leads and die pads.

of forming a HSQFN (High Speed Quad Flat Pack) package, comprising:  
a leadframe with bonding pads;  
a die;  
bonding wires between said die and said bonding pads;  
a compound having electrical connection; and  
a die by compound from a substrate;  
the method comprising:  
removing said leadframe from the compound;  
exposing a lower surface of said leadframe to expose a lower surface of said die;  
separating said die from said leadframe;  
and  
forming individual packages;  
and said compound.

The method of claim 1, further comprising:  
removing said leadframe to form an individual package;  
said leadframe, therefrom;  
and die pads.

of forming a HSQFN (High Speed Quad Flat Pack) package, comprising:  
a leadframe with bonding pads;  
a die;  
bonding wires between said bonding pads and said die;  
a compound having electrical connection; and  
a die by compound from a substrate;  
removing said leadframe from the compound to expose a lower surface of the die;  
thereby separating said die from the compound;  
and  
each individual package.  
The method of claim 1, further comprising:  
forming a leadframe to form an integrated circuit;  
said leadframe, thereon forming bonding pads and die pads.

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3. The method of claim 1, furthering comprising punching said leadframe to form an inward indentation portions in said leadframe, thereby forming said bonding pads and die pads.

4. The method of claim 1, wherein said die is attached by adhesive material.

5. The method of claim 4, wherein said adhesive material includes epoxy.

6. The method of claim 1, wherein said bonding wires includes gold.

7. A method of forming a HSQFN (High Stand-off Quad Flat Non-leaded) package, comprising:  
performing two stages of etching to etch a leadfram from a different surface, wherein further comprising performing die bonding, wire bonding and molding between said two stages of etching;  
wherein a first etching of said two stages of etching comprising forming an inward indentation portion of said leadframe from a first side of said leadframe to define die pads and bonding pads; and

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wherein a second etching of said two stages of etching comprising separating said die pads and bonding pads by etching from a second side of said leadframe.

8. The method of claim 7, furthering comprising separating each individual package by cutting said leadframe and compound formed by said molding.

9. A HSQFN (High Stand-off Quad Flat Non-leaded) package, comprising:

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a leadframe having a die pad and bonding pads, wherein said die pad is designed to carry a die adhesived thereon by adhesive material, wherein said die pad and bonding pads are separated;

a plurality of bonding wires connected between said bonding pads and said die for electrical communication; and

molding compound encompasses said die, said bonding wires and a first surface of said lead frame, leaving the terminal of said bonding pads and the lower surface of said die pad exposed out of said compound for providing excellent thermal dissipation from said packages, wherein said exposed bonding pads is used for communication terminal for said package.

11. The HSQFN package of claim 10, wherein said adhesive material includes epoxy.

12. The HSQFN package of claim 9, wherein said bonding wires includes gold.

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